SK-AM68 Processor Start Kit User's Guide



ABSTRACT

This document provides the SK-AM68 capabilities and interface details.



This design incorporates HDMI® technology.

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1 Introduction

1.1 Inside the Box

The SK-AM68 Processor Starter Kit includes:

- SK- AM68 EVM (two PCB board solution)
- Micro-SD Card
- USB Cable (Type-A to Micro-B) for serial terminal/logging
- Paper Card with Start-up Link/Support Information

The EVM is powered from a Type-C power supply, but is NOT INCLUDED. For more information on the types of supplies recommended with the EVM, see Table 2-1

1.2 Key Features and Interfaces

- Processor
 - Texas Instruments Jacinto AM68 Super-Set device
- · Optimized Power Management Solution
 - Dynamic Voltage Scaling
 - Multiple Clock and Power Domains
- Memory
 - 16GByte LPDDR4 DRAM (2133 MHz)
 - 512 Mb Non-Volatile Flash, Octal-SPI NOR
 - Multimedia Card (MMC)/Secure Digital Card (Micro SD) Cage, UHS-I
- USB
 - USB3.1 (Gen1) Hub to 3x Type A (Host)
 - USB3.1 (Gen1) Type C (DFP mode)
 - USB2.0 Micro B (for Quad UART-over-USB Transceiver)
- Display
 - VESA Display Port (v1.4), supports 2K HD
 - DVI (v1.0) via HDMI Type A, supports 1080p
- Wired Network
 - Gigabit Ethernet (RJ45 Connector)
 - 4x CAN-FD Headers (1x3)
- · Camera Interfaces
 - 2x 22-Pin Flex Cable Interface (CSI-4L)
 - 40-pin High Speed Connector (dual CSI-4L, I2C, GPIO, and so forth)
- Expansion/Add-on
 - M.2 Key M Interface (PCIe/Gen3 x 2 Lane)
 - 40-pin Header (2x20) (I2C, SPI, UART, I2S, GPIO, PWM, and so forth)
 - Fan Header (5 V)
- · User Control/Indication
 - Pushbuttons (Reset, Power/User Defined)
 - LEDs (Power, User Defined, Serial Port)
 - User Configuration (Boot Mode)
 - External JTAG/Emulator Support (20-pin Header)
- REACH and RoHS Compliant
- EMI/EMC Radiation Compliant

1.3 Thermal Compliance

There is elevated heat on the processor/heatsink, use caution particularly at elevated ambient temperatures!

Although the processor/heatsink is not a burn hazard, caution should be used when handling the EVM due to increased heat in the area of the heatsink



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Caution

Caution Hot surface. Contact may cause burns. Do not touch!

1.4 EMC, DMI, and ESD Compliance

Components installed on the product are sensitive to Electrostatic Discharge (ESD). It is recommended this product be used in an ESD controlled environment. This may include a temperature and/or humidity controlled environment to limit the buildup of ESD. It is also recommended to use ESD protection such as wrist straps and ESD mats when interfacing with the product.

The product is used in the basic electromagnetic environment as in laboratory condition and the applied standard will be as per EN IEC 61326-1:2021.

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2 User Interfaces

Figure 2-1 and Figure 2-2 identify the key user interfaces on the EVM (top and bottom view).

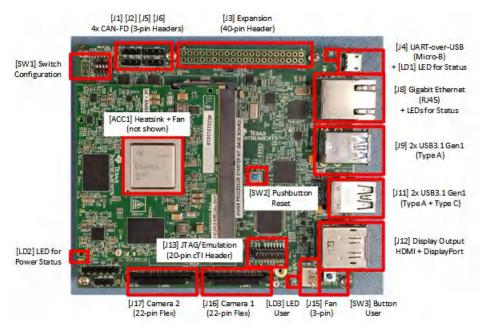


Figure 2-1. User Interfaces (Top)

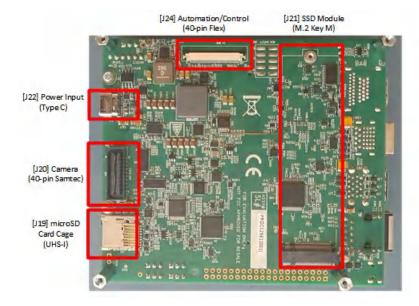


Figure 2-2. User Interfaces (Bottom)

2.1 Power Input

A power supply is not included with the EVM and must be purchased separately.

External Power Supply or Power Accessory Requirements:

- Nominal Output Voltage: 5-20VDCMaximum Output Current: 5000 mA
- Efficiency Level V

Note

TI recommends using an external power supply or power accessory that complies with applicable regional safety standards such as (by example) UL, CSA, VDE, CCC, PSE, and so forth.

2.1.1 Power Input [J22] With LED for Status [LD2]

The dedicated power input connector is a USB Type C connector [J22] with Power Delivery 3.0 support. The input can accept wide range of input voltages (5 V to 20 V). The exact power required for the SK EVM is largely dependent on the application and the connected peripherals. The recommended supplies are listed in Table 2-1. These supplies are 20 V Type C supplies capable of supplying up to 60W of power (20VDC at 3A). The minimum supply required is 15W supply (5VDC at 3A). However, a 5 V supply may limit available processing with the processor as well as limit some of the available peripherals. USB peripherals require VBUS and depending on their power needs, may have too much voltage drop from a 5 V input supply. This is a reason higher voltage supply is recommended.

There are many USB Type C power supply manufactures and models available in the market, and it is not possible to test the SK EVM with every combination.

Table 2-1 lists a few recommended supplies the EVM has tested.

Table 2-1. Recommended External Power Supply

Manufacturer	Part #	Digikey #
GlobTek, Inc.	TR9CZ3000USBCG2R6BF2	1939-1794-ND
Qualtek	QADC-65-20-08CB	Q1251-ND

2.1.2 Power Budget Considerations

The exact power required for the EVM is largely dependent on the application, usage of the on-board peripherals, and power needs of add-on devices. Table 2-2 shows the designs power allocations. (Again, the input supply must be capable of supplying the power needs for your application.)

Table 2-2. Power Supply Allocation

Function	Power	Description
Processor Core	Up to 15W	Processor, Memory
On-board Peripherals	Up to 3W	SD card, Ethernet, Logic, and so forth
USB Port(s)	Up to 20W	USB Hub Type A Ports(2.8A at 5V) Type C Port(1.5A at 5V)
Camera Ports	Up to 2W	Cam Ports (0.5A at 3.3V)
Expansion Interface(s)	Up to 20W	M.2 M Key (3A at 3.3V) 40p Expansion(2A at 3.3V,1.5A at 5V)
Display(s)	Up to 3W	HDMI Transceiver HDMI Panel(55mA at 5V) DP Panel (0.5A at 3.3V)

2.2 User Inputs

The EVM supports several mechanisms for the user to configure, control, and provide input to the system.

2.2.1 Board Configuration Settings [SW1]

Dip Switch [SW1] is used to configure different options available on the EVM, including processor boot mode.

Table 2-3. Processor Bootmode Settings [SW1 Switch 1-3]

TDA4VM Boot Source	SW1.1	SW1.2	SW1.3
MicroSD Card [J19]	OFF	OFF	OFF
Non-Volatile Flash (xSPI)	OFF	OFF	ON
Reserved	OFF	ON	ON

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Table 2-3. Processor Bootmode Settings [SW1 Switch 1-3] (continued)

TDA4VM Boot Source	SW1.1	SW1.2	SW1.3
UART [J4] (for Flashing)	ON	OFF	ON
No Boot (JTAG/Emulator)	ON	OFF	OFF
Ethernet[J8]	OFF	ON	OFF

2.2.2 Reset Power Down Pushbutton [SW2]

When pressed [SW2], the EVM is issued a Power-On (Cold) Reset, and is held in reset until the button is released.

If the pushbutton is held longer than 5 seconds, the system will power down. The system can be restarted by either pressing the User Pushbutton [SW3] or by cycling power to the board.

2.2.3 User Pushbutton [SW3] With User LED Indication [LD3]

The pushbutton [SW3] can be used for several different functions.

Function 1: System Wake from Shutdown. After power down using either Pushbutton [SW2] or Software-Initiated (WKUP GPIO0 69), pressing pushbutton [SW3] will re-enable and boot the EVM.

Function 2: Power Management Enable. The pushbutton [SW3] is connected with Power Management IC (EN), and can be programmed for different power related functions (ex. Wake from Sleep).

Function 3: User Defined Input/Interrupt. The pushbutton [SW3] is connected with the TDA4VE processor (WKUP GPIO0 69), and can be programmed for variety of user input/interrupt needs.

A red LED [LD3] is available as user indicator, and is controlled via the processor (WKUP GPIO0 29)

2.3 Standard Interfaces

The EVM provides industry standard interfaces/connectors to connect a wide variety of peripherals. As these interfaces are standard, specific pin information is not provided in this document.

2.3.1 Uart-Over-USB [J4 With LED for Status [LD1]

Four UART ports of the processor are interfaced with UART-over-USB transceiver on the EVM. When the EVM's USB micro-B connector (J4) is connected to a Host-PC using supplied USB cable (Type-A to Micro-B), the computer can establish Virtual Com Port(s) which can be used with any terminal emulation application. Virtual Com Port drivers for the transceiver (CP2108-B02-GM) can be obtained fromhttps://www.silabs.com/developers/usb-touart-bridge-vcp-drivers.

Once installed, the Host-PC will create four Virtual Com Ports. Depending on the other Host-PC resources available - the Virtual COM Ports not be located at COM1-4. However, they will remain in the same numerical order.

Table 2-4. UART to COM Port Mapping

TDA4VE UART	Host-PC COM Port
WKUP_UART0	COM 1
MCU_UART0	COM 2
UART8	COM 3
UART2	COM 4

The circuit is powered through BUS power and therefore the COM connection not be lost when the EVM power is removed. An LED [LD1] is used to indicate an active COM connection with Host-PC.

2.3.2 Gigabit Ethernet [J8] With Integrated LEDs for Status

A wired Ethernet network is supported on the EVM via Figure 2-3, and is compatible with IEEE 802.3 10BASETe,100BASE-TX, and 1000BASE-T specifications. The connector includes status indicators for link and activity.

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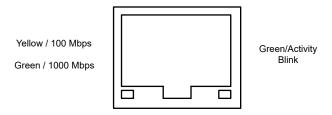


Figure 2-3. RJ45 LED Indicators [J8]

Power-Over-Ethernet (PoE) is not supported.

2.3.3 JTAG Emulation Interface [J13]

The EVM supports JTAG emulation/debugger through a dedicated emulation connector [J13] on the baseboard. The connector is aligned with the Texas Instrument 20-pin CTI header standard (2x20, 1.27mm pitch), and is compatible with Texas Instruments modules (XDS110, XDS200, XDS560v2) and 3rd party modules.

Table 2-5. Expansion Header Pin Definition [J9]

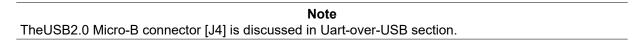
Pin No.	Pin Name	Description (Processor Pin #)	Dir
1	TMS	Test Mode Select(TMS)	Input
2	TRSTn	Test Reset	Input
3	TDI	Test Data Input	Input
4	TDIS	Target Disconnect	Output
5	Vref	Target Voltage Detect, 3.3V	Output
6	<no pin=""></no>	No pin/Key	
7	TDO	Test Data Output	Output
8	GND	Ground	
9	RTCK	Test Clock Return	Output
10	GND	Ground	
11	тск	Test Clock	Input
12	GND	Ground	
13	EMU0	Emulation Pin 0	Bi-Dir
14	EMU1	Emulation Pin 1	Bi-Dir
15	RESETz	Target Reset	Input
16	GND	Ground	
17		Open	
18		Open	
19		Open	
20	GND	Ground	

Note

In the DIR column, output is to the JTAG module, input is from the JTAG module. Bi-Dir signals can be configured as either input or output.

2.3.4 USB3 1 Gen1 Interfaces [J9] [J11]

The EVM supports three USB3.1 Gen1 Type A ports [J9][J11], which operate in Host mode. The combined VBUS output for these ports is limited to 2.8A. Also supported is one USB3.1 Gen1 Type C interface [J11], which can function as DFP. The VBUS output for this port is limited to 1.5A.



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Note

The VBUS power capability assumes the selected input supply is capable of supplying power for both SK-AM68 system and connected peripherals.

Note

An example optional add-on USB Camera module for this interface is the Logitech USB C270.

Note

The maximum length for the IO cables should not exceed 3 meters.

2.3.5 Stacked DisplayPort and HDMI Type A [J12]

The EVM supports DisplayPort panel via standard DP cable interface [J12]. The interface supports resolutions to 2K HD (1920x1080). A second display interface is supported via HDMI connector [J12], and supports resolutions up to 2K HD (1920x1080). The interface is DVI, and therefor does not support the integrated audio. Both DisplayPort and HDMI interfaces can be used simultaneously.

2.3.6 M 2 Key M Connector [J21] for SSD Modules

The EVM supports a Mini-PCle M.2, Key M slot (2280) for expansion modules [J21]. This expansion interface is primarily used for Solid State Drives (SSD), and supports the following interfaces: PCle (2L) and I2C.

2.3.7 MicroSD Card Cage [J19]

The EVM supports a micro-SD card cage. It supports UHS-1 class memory cards, including SDHC and SXDC. The connector is a PUSH-PUSH connector, meaning you push to insert the card and push again to remove the card.

A MicroSD Card is included with the EVM kit.

2.4 Expansion Interfaces

The EVM supports expansion interfaces that have non-standard/custom pinouts. Each of those interfaces are introduced and specific pin information is provided.

2.4.1 Heatsink [ACC1] With [J15] Fan Header

The heatsink supports cooling of the device at ambient temperatures which will be mounted on the processor. If your environment or use case requires additional cooling, a fan can be added to the Heatsink.

The fan connector is a 3-pin header (WURTH ELEKTRONIK, Part number 61900311121).

Table 2-6. Fan Header Pin Definition [J15]

Pin #	Pin Name	Description	Direction
1	<open></open>	Unconnected	N/A
2	5V	Main 5V supply	Output
3	GND	Ground	

2.4.2 CAN-FD Connector(s) [J1] [J2] [J5] [J6]

The EVM supports four (4x) CAN Bus interfaces.

Table 2-7. CAN-FD Interface Assignment

14.0.0 = 11 07.11 1 = 11.001.400 7.001.9.11.101.1			
Connector Ref	ctor Ref TDA4VE Resource		
J1	MCU_CAN0		
J2	CAN7		
J5	MCU_CAN1		
J6	CAN6		

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Each Controller Area Network (CAN) Bus interface is supported on a 3-pin, 2.54 mm pitch header. The interface meets ISO 11898-2 and ISO 11898-5 physical standards, and supports CAN and optimized CAN-FD performance up to 8 Mbps. Each includes CAN Bus end-point termination. If the EVM is included in a network with more than two nodes, the termination my need to be adjusted.

Table 2-8. CAN-FD Header Pin Definition [J1][J2][J5][J6]

	Pin#	Pin Name	Description	Direction
	1	CAN-H	High-Level CAN Bus Line	Bi-Dir
	2	GND	Ground	
	3	CAN-L	Low-Level CAN Bus Line	Bi-Dir

2.4.3 Expansion Header [J3]

The EVM includes a 40-pin (2x20, 2.54mm pitch) expansion interface [J3]. The expansion connector supports variety of interfaces including: I2C, serial peripheral interface (SPI), I2S with Audio clock, UART, pulse width modulator (PWM), and GPIO. All signals on the interfaces are 3.3 V levels.

Table 2-9. Expansion Header Pin Definition [J3]

Pin #	Pin Name	Description(Processor Pin #)	Dir
1	Power	Power,3.3 V	Output
2	Power	Power,5.0 V	Output
3	I2C_SDA	I2CBus #4, Data (AF28)	Bi-Dir
4	Power	Power,5.0 V	Output
5	I2C_SCL	I2CBus #4, Clock (AD25)	Bi-Dir
6	GND	Ground	
7	GP_CLK/GPIO	REFCLK0/WKUP_GPIO0_66 (G25)	Bi-Dir
8	UART_TXD	UART#5 Transmit (W25)	Output
9	GND	Ground	
10	UART_RXD	UART#5 Receive (AC24)	Input
11	GPIO	GPIO0_42 (U24)	Bi-Dir
12	I2S_SCLK	McASP#1 ACLKX (AA24)	Bi-Dir
13	GPIO	GPIO0#36 (W24)	Bi-Dir
14	GND	Ground	
15	GPIO	WKUP_GPIO0_49 (K26)	Bi-Dir
16	GPIO	GPIO0#3 (AE28)	Bi-Dir
17	Power	Power,3.3V	Output
18	GPIO	AUDIO_EXT_REFCLK0(AD24)	Bi-Dir
19	SPI_MOSI	MCU SPI#0 Data 0 (E24)	Bi-Dir
20	GND	Ground	
21	SPI_MISO	MCU SPI#0 Data 1 (C28)	Bi-Dir
22	GPIO	WKUP_GPIO0_67 (J27)	Bi-Dir
23	SPI_SCLK	MCU SPI#0 Clock (D26)	Bi-Dir
24	SPI_CS0	MCU SPI #0 Chip Select 0 (C27)	Bi-Dir
25	GND	Ground	
26	SPI_CS1	MCU SPI #0 Chip Select 2 (D25)	Bi-Dir
27	ID_SDA	Wkup I2C Data (H27)	Bi-Dir
28	ID_SCL	Wkup I2C Clock (H24)	Bi-Dir
29	GPIO	WKUP_GPIO0_56 (G27)	Bi-Dir
30	GND	Ground	
31	GPIO	WKUP_GPIO0_57(J26)	Bi-Dir
32	PWM0	PWM3_A (T25)	Output

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Table 2-9. Expansion Header Pin Definition [J3] (continued)

Pin #	Pin Name	Description(Processor Pin #)	Dir
33	PWM1	PWM0_A (AE27)	Output
34	GND	Ground	
35	I2S_FS	McASP #1 FSX (V28)	Bi-Dir
36	GPIO	GPIO0_41 (T23)	Bi-Dir
37	GPIO	GPIO0_27 (V26)	Bi-Dir
38	I2S_DIN	McASP #1 (T28)	Bi-Dir
39	GND	Ground	
40	I2S_DOUT	McASP #1 (U25)	Bi-Dir

Note

In the DIR column, output is to the expansion module, input is from the expansion module. Bi-Dir signals can be configured as either input or output.

Note

All processor signals on the Expansion connector can support other functions including GPIO. For full list of functions available on each pin, see the AM68 Processors Data Manual. Functions like UART and PWM set as INPUT or OUTPUT can be BI-DIR when configured as GPIO

2.4.4 Camera Interface 22-Pin Flex Connectors [J16][J17]

The EVM supports two (2) 22-pin flex (0.5mm pitch) connectors [J16][J17] for interfacing with camera modules. Each camera interface provides MIPI CSI-2interface (4Lane), Clock/Control signals, and power (3.3 V) to the camera.

To enable camera modules with same addressing to be used simultaneously, I2C mux is used to select each camera. The voltage level for Clock/Control signals is selectable between 1.8 V/3.3 V.

Table 2-10. Camera 1 Flex Pin Definition [J16]

Pin #	Pin Name	Description	Dir
1/ 1A	Power	Power, 3.3V	Output
3/ 2A	I2C_SDA	I2C Data # 1, Mux 0	Bi-Dir
5/ 3A	I2C_SCL	I2C Clock #1, Mux 0	Output
7/4A	GND	Ground	
9/ 5A	CAM0_AUX	AUX (WKUP_GPIO0_88)	Bi-Dir
11/ 6A	CAM0_PWDN	Pwr-Dwn(IO expander)	Output
13/ 7A	GND	Ground	
15/ 8A	CSI0_D3_P	CSIPort 0 Data Lane 3	Input
17/ 9A	CSI0_D3_N	CSIPort 0 Data Lane 3	Input
19/10A	GND	Ground	
21/ 11A	CSI0_D2_P	CSIPort 0 Data Lane 0	Input
23 / 12A	CSI0_D2_N	CSIPort 0 Data Lane 0	Input
25 / 13A	GND	Ground	
27 / 14A	CSI0_CLK_P	CSIPort 0 CLK	Input
29 / 15A	CSI0_CLK_N	CSIPort 0 CLK	Input
31 / 16A	GND	Ground	
33 / 17A	CSI0_D1_P	CSIPort 0 Data Lane 1	Input
35 / 18A	CSI0_D1_N	CSIPort 0 Data Lane 1	Input
37 / 19A	GND	Ground	
39 / 20A	CSI0_D1_P	CSIPort 0 Data Lane 0 Input	
41 / 21A	CSI0_D1_N	CSIPort 0 Data Lane 0	Input

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Table 2-10. Camera 1 Flex Pin Definition [J16] (continued)

Pin #	Pin Name	Description	Dir
43 / 22A	GND	Ground	

Table 2-11. Camera 2 Flex Pin Definition [J17]

Pin #	PinName	Description	Dir
1/ 1A	Power	Power, 3.3V	Output
3/ 2A	I2C_SDA	I2C Data # 1, Mux 1	Bi-Dir
5/ 3A	I2C_SCL	I2C Clock #1, Mux 1	Output
7/4A	GND	Ground	
9/ 5A	CAM1_AUX	AUX (WKUP_GPIO0_70)	Bi-Dir
11/ 6A	CAM1_PWDN	Pwr-Dwn(IO expander)	Output
13/ 7A	GND	Ground	
15/ 8A	CSI1_D3_P	CSIPort 1 Data Lane 3	Input
17/ 9A	CSI1_D3_N	CSIPort 1 Data Lane 3	Input
19/ 10A	GND	Ground	
21/ 11A	CSI1_D2_P	CSIPort 1 Data Lane 0	Input
23 / 12A	CSI1_D2_N	CSIPort 1 Data Lane 0	Input
25 / 13A	GND	Ground	
27 / 14A	CSI1_CLK_P	CSIPort 1 CLK	Input
29 / 15A	CSI1_CLK_N	CSIPort 1 CLK	Input
31 / 16A	GND	Ground	
33 / 17A	CSI1_D1_P	CSIPort 1 Data Lane 1	Input
35 / 18A	CSI1_D1_N	CSIPort 1 Data Lane 1	Input
37 / 19A	GND	Ground	
39 / 20A	CSI1_D1_P	CSIPort 1 Data Lane 0	Input
41 / 21A	CSI1_D1_N	CSIPort 1 Data Lane 0	Input
43 / 22A	GND	Ground	

Note

In the DIR column, output is to the camera module, input is from the camera module. Bi-Dir signals can be configured as either input or output.

2.4.5 Camera Interface 40-Pin High Speed [J20]

The EVM includes a 40-pin (2x20, 2.54 mm pitch) high speed camera interface [J20]. The expansion connector supports two CSI-2 (4 Lanes each), power, and control signals (I2C, GPIO, and so forth): All control signals are configurable for 3.3 V or 1.8 V voltage levels.

Table 2-12. Camera IO Voltage Control

I2C IO Expander (P00)	CameralO Level
Lowor '0'	1.8V (Default)
Highor '1'	3.3V

Table 2-13. 40-Pin High-Speed Camera Expansion Pin Definition [J20]

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Pin #	Pin Name	Description(Processor Pin #)	Dir	
1	Power		Output	
2	I2C_SCL	I2CBus #1, Clock (AC25)	Bi-Dir	
3	Power		Output	
4	I2C_SDA	I2CBus #1, Data (AD26)	Bi-Dir	
5	CSI0_CLK_P	CSIPort 0 Clock	Input	
6	GPIO/PWMA	WKUP_GPIO0_32(B20)	Bi-Dir	

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Table 2-13. 40-Pin High-Speed Camera Expansion Pin Definition [J20] (continued)

Pin #	Pin Name	Description(Processor Pin #)	Dir
7	CSI0_CLK_N	CSIPort 0 Clock	Input
8	GPIO/PWMB	WKUP_GPIO0_36 (C20)	Bi-Dir
9	CSI0_D0_P	CSIPort 0 Data Lane 0	Input
10	REFCLK	MCU CLKOUT0(F25)	Bi-Dir
11	CSI0_D0_N	CSI Port 0 Data Lane 0	Input
12	GND	Ground	
13	CSI0_D1_P	CSI Port 0 Data Lane 1	Input
14	RESETz	FROM IO EXPANDER	Output
15	CSI0_D1_N	CSI Port 0 Data Lane 1	Input
16	GND	Ground	
17	CSI0_D2_P	CSI Port 0 Data Lane 2	Input
18	GPIO	WKUP_GPIO0_37 (A20)	Bi-Dir
19	CSI0_D2_N	CSI Port 0 Data Lane 2	Input
20	GPIO	WKUP_GPIO0_38 (D20)	Bi-Dir
21	CSI0_D3_P	CSI Port 0 Data Lane 3	Input
22	GPIO	WKUP_GPIO0_35 (G20)	Bi-Dir
23	CSI0_D3_N	CSI Port 0 Data Lane 3	Input
24	GND	Ground	
25	CSI1_CLK_P	CSI Port 1 Clock	Input
26	CSI1_D3_P	CSI Port 1 Data Lane 3	Input
27	CSI1_CLK_N	CSI Port 1 Clock	Input
28	CSI1_D3_N	CSI Port 1 Data Lane 3	Input
29	CSI1_D0_P	CSI Port 1 Data Lane 0	Input
30	Power	Power, 3.3V	Output
31	CSI1_D0_N	CSI Port 1 Data Lane 0	Input
32	Power	Power, 3.3V	Output
33	CSI1_D1_P	CSI Port 1 Data Lane 1	Input
34	Power	Power, 3.3V	Output
35	CSI1_D1_N	CSI Port 1 Data Lane 1	Input
36	Power	Power, 3.3V	Output
37	CSI1_D2_P	CSI Port 1 Data Lane 2	Input
38	Power	Power, IO Level (1.8 or 3.3V)	Output
39	CSI1_D2_N	CSI Port 1 Data Lane 2	Input
40	Power	Power, IO Level (1.8 or 3.3V)	Output

Note

In the DIR column, output is to the expansion module, input is from the expansion module. Bi-Dir signals can be configured as either input or output.

2.4.6 Automation and Control Connector [J24]

The EVM supports an interface to allow for automated control of the system, including functions like on/off, reset, and boot mode settings.

Table 2-14. Test Automation Interface Pin Definition [J24]

Pin Pin Name		Description(Processor Pin #)	Dir
1	Power	Power,3.3 V	Output
2	Power	Power,3.3 V	Output



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Table 2-14. Test Automation Interface Pin Definition [J24] (continued)

Pin	Pin Name	Description(Processor Pin #)	Dir
3	Power	Power,3.3 V	Output
4-6	<open></open>		N/A
7	GND	Ground	
8-15	<open></open>		N/A
16	GND	Ground	
17-24	<open></open>		N/A
25	GND	Ground	
26	POWERDOWNz	EVM Power Down	Input
27	PORz	EVM Power-On/Cold Reset	Input
28	RESETz	EVM Warm Reset	Input
29	<open></open>		N/A
30	INT1z	MCU_ADC1_AIN0 (P25)	Input
31	INT2z	MCU_ADC1_AIN1 (R25)	Bi-Dir
32	<open></open>		N/A
33	BOOTMODE_RSTz	Bootmode Buffer Reset	Input
34	GND	Ground	
35	<open></open>		N/A
36	I2C_SCL	MCU I2C Bus #0, Clock (G24)	Bi-Dir
37	BOOTMODE_SCL	Bootmode Buffer I2C Clock	Input
38	I2C_SDA	MCU I2C Bus #0, Data (J25)	Bi-Dir
39	BOOTMODE_SDA	Bootmode Buffer I2C Data	Bi-Dir
40	GND	Ground	
41	GND	Ground	
42	GND	Ground	

Note

In the DIR column, output is to the test automation module, input is from the test automation module. Bi-Dir signals can be configured as either input or output.

Note

The signal polarity is identified with a trailing 'z' in the Pin Name, which indicates the signal is active LOW. For example, POWERDOWNz is an active low signal, meaning '0' = EVM is Powered Down, '1' = EVM is NOT Powered Down.

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3 Circuit Details

This section provides additional details on the EVM design and processor connections.

3.1 Top Level Diagram

Figure 3-1 shows the functional block diagram of the EVM Board.

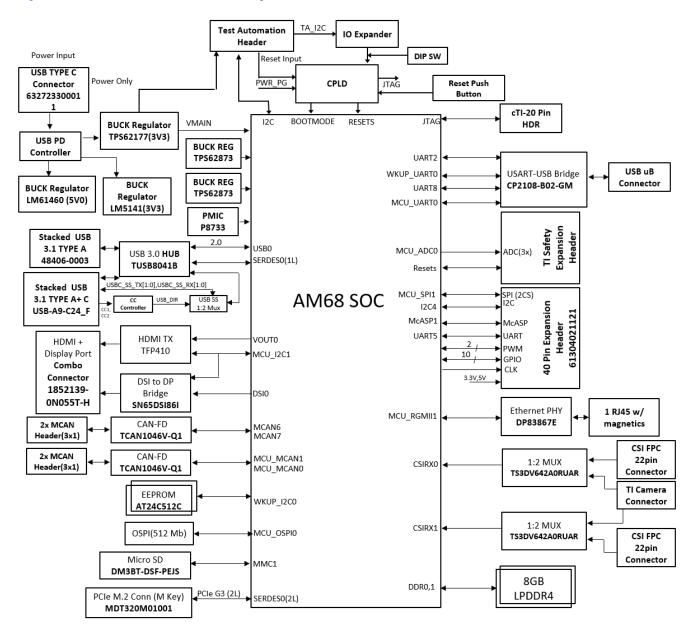


Figure 3-1. SK-AM68 EVM Functional Block Diagram

3.2 AM68 SK EVM Interface Mapping

Table 3-1 is provided below.

Table 3-1. Interface Mapping Table

Connected Peripheral	Processor Resources	Components/ Part Numbers
Memory,LPDDR4 DRAM	DDR0, DDR1	Micron MT53E2G32D4DE-046 AUT:C
Memory,xSPI NOR Flash	MCU_OSPI0	CypressS28HS512TGABHM010
Micro-SDCard Cage	MMC1	

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Table 3-1. Interface Mapping Table (continued)

Connected Peripheral	Processor Resources	Components/ Part Numbers
EEPROM, Board Identification	WKUP_I2C0	MicrochipTech AT24C512C
Wired Ethernet	MCU_RGMII1, MCU_MDIO	Texas Instruments DP83867E
USB Type C + CC Controller	USB0(SERDES0)	Texas Instruments TUSB321
USB Type A (3x)	USB0(SERDES0)	Texas Instruments TUSB8041
HDMI	DPI0, MCU_I2C1	Texas Instruments TFP410
DisplayPort	DSI0, MCU_I2C1	Texas Instruments SN65DSI86
PCIe- M.2 Socket (M-Key 2280)	PCIe1 (SERDES0), I2C0	
CSIRx Interface	CSI0,CSI1, I2C1	
UART Terminal (UART-to-USB)	WKUP_UART0,MCU_UART0, UART8, UART2	SiliconLabs CP2108
CAN(4x)	MCU_MCAN0, MCU_MCAN1, MCAN6, MCAN7	Texas Instruments TCAN1046V
Expansion Header (40-pin)	McASP1, MCU_SPI1, UART5, I2C4	
Expansion Header (10-pin)	MCU_ADC0,RESETs	
TestAutomation Header	MCU_I2C0	

3.3 I2C Address Mapping

Table 3-2 provides the complete I2C address mapping details on EVM.

Table 3-2. I2C Mapping Table

Tuble 0 2. 120 mapping Tuble				
Connected Peripheral	Processor Resources		Components/ Part Numbers	
	I2C Port	I2CAddress		
Power Management IC	WKUP_I2C0	0x60	Texas Instruments LP8733	
Buck Regulator	WKUP_I2C0	0x40	Texas Instruments TPS62873	
Buck Regulator	WKUP_I2C0	0x43	Texas Instruments TPS62873	
EEPROM, Board Id SOM	WKUP_I2C0	0x51	Microchip Tech AT24C512C	
EEPROM, Board Id Base Board	WKUP_I2C0	0x52	Microchip Tech AT24C512C	
ExpansionHeader (40p)	WKUP_I2C0	Add-on		
Current Monitor IC	MCU_I2C0	0x40-0x45	Texas Instruments INA231	
Automation Header	MCU_I2C0			
Bootmode IO expander	MCU_I2C0	0x20	Texas Instruments TCA6408	
HDMIDDC	MCU_I2C1	Add-on		
eDP Bridge	MCU_I2C1	0x2C	Texas Instruments SN65DSI86	
Input PD Controller	I2C0	0x20	Texas Instruments TPS25750	
PCIe M.2 Key E/M	I2C0	Add-on		
Camera Expansion	I2C0	0x70Add-on	Texas Instruments TCA9543A	
CSI FPC Conn	I2C1	Add-on		
Expansion Header (40p)	I2C4	Add-On		
	1			

3.4 GPIO Mapping

The General Purpose IOs (GPIO) of the AM68 SoC are segmented into two major groups, WKUP and MAIN. For this design, the is no functional difference between the GPIOs. Table 3-3 describes the processor's GPIO mapping to the EVM peripherals and provides the default settings.

Circuit Details

Table 3-3 GPIO Mapping Table

Droopper Din Name		able 3-3. GPIO Mapping		Domarka
Processor Pin Name	GPIO	Function	Dir/ Level	Remarks
WKUP_GPIO0_10	WKUP_GPIO0_10	ADC external trigger from TI safety header(Default connection)/CLKREQ#	Input	External ADC Trigger Signal
WKUP_GPIO0_11	WKUP_GPIO0_11	40pin Expansion HeaderSignal (REFCLK0/ GPIO)	Output	Expansion Board Specific (Pin 10)
WKUP_GPIO0_15	WKUP_GPIO0_15	MCU SPI1 signal	Output	SPI chip select Signal for 40 pin Header
MCU_OSPI0_CSn1	WKUP_GPIO0_28	Enable for eFUSE Programming Supply	Output	'0'- Disabled(Default) '1'- Enabled
MCU_OSPI0_CSN2	WKUP_GPIO0_29	User LED [LD2]	Output	'0' – LED [LD2] is OFF (default) '1' – LED [LD2] is ON
MCU_OSPI1_CLK	WKUP_GPIO0_31	Ethernet PHY Interrupt	Input	'0' – Active Interrupt Request '1' – No Interrupt Request (default)
MCU_OSPI1_LBCLKO	WKUP_GPIO0_32	GPIO Signals for CSI expansion connector	Bi-Dir	ExpansionBoard Specific (Pin 6)
MCU_OSPI1_DQS	WKUP_GPIO0_33	SW2 Pushbutton	Output	'0' – SW2 is Pressed '1' – SW2 is NOT Pressed (default)
MCU_OSPI1_D0	WKUP_GPIO0_34	SW3 Pushbutton	Input	'0' – SW3 is Pressed '1' – SW3 is NOT Pressed (default)
MCU_OSPI1_D1	WKUP_GPIO0_35	40pin Expansion Header Signal (GPIO)	Bi-Dir	ExpansionBoard Specific (Pin 22)
MCU_OSPI1_D2	WKUP_GPIO0_36	GPIO Signals for CSI expansion connector	Bi-Dir	ExpansionBoard Specific (Pin 8)
MCU_OSPI1_D3	WKUP_GPIO0_37	GPIO Signals for CSI expansion connector	Bi-Dir	ExpansionBoard Specific (Pin 18)
MCU_OSPI1_CSN0	WKUP_GPIO0_38	CSI Expansion Signal (GPIO)	Bi-Dir	CSI2 Expansion Board Specific (Pin 20)
MCU_OSPI1_CSN1	WKUP_GPIO0_39	Power Management IC Interrupt	Input	'0'- Active Interrupt Request '1'- No Interrupt Request (default)
WKUP_GPIO0_49	WKUP_GPIO0_49	40pin Expansion Header Signal (GPIO)	Bi-Dir	Expansion Board Specific (Pin 15)
MCU_SPI0_CLK	WKUP_GPIO0_54	MUX select	Output	'0' – A to B1 port selected '1' – A to B2 port selected
WKUP_GPIO0_56	WKUP_GPIO0_56	40pin Expansion Header Signal (GPIO)	Bi-Dir	Expansion Board Specific (Pin 29)
WKUP_GPIO0_57	WKUP_GPIO0_57	40pin Expansion Header Signal (GPIO)	Bi-Dir	Expansion Board Specific (Pin 31)
WKUP_GPIO0_66	WKUP_GPIO0_66	40pin Expansion Header Signal (GPIO)	Bi-Dir	Expansion Board Specific (Pin 7)



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Table 3-3. GPIO Mapping Table (continued)

Table 3-3. GPIO Mapping Table (continued)								
Processor Pin Name	GPIO	Function	Dir/ Level	Remarks				
WKUP_GPIO0_67	WKUP_GPIO0_67	40pin Expansion Header Signal (GPIO)	Bi-Dir	Expansion Board Specific (Pin 22)				
MCU_SPI0_D1	WKUP_GPIO0_69	System Power Down	Output	'0' - Normal Operation (default) '1' - System Power Down/Off				
MCU_SPI0_CS0	WKUP_GPIO0_70	Camera #1 Flex Signal (GPIO)	Bi-Dir	Camera Specific (Pin 5a)				
MCU_ADC1_AIN0	WKUP_GPIO0_79	Test Automation Interrupt #1	Input	'0' - To Be Defined by User '1' - To Be Defined by User (default)				
MCU_ADC1_AIN1	WKUP_GPIO0_80	Test Automation Interrupt #2	Input	'0' - To Be Defined by User '1' - To Be Defined by User (default)				
PMIC_POWER_EN1	WKUP_GPIO0_88	Camera #0 Flex Signal (GPIO)	Bi-Dir	Camera Specific (Pin 5a)				
EXTINTN	GPI00_0	HDMI Monitor Detect	Input	Active High Signal '0' – No Monitor Detected (default) '1' – Monitor Detected				
MCAN13_TX	GPIO0_3	40pin Expansion Header Signal (GPIO)	Bi-Dir	Expansion Board Specific (Pin 16)				
MCAN1_TX	GPIO0_27	40pin Expansion Header Signal (GPIO)	Bi-Dir	Expansion Board Specific (Pin 37)				
MCASP0_AXR8	GPIO0_36	40pin Expansion Header Signal (GPIO)	Bi-Dir	Expansion Board Specific (Pin 13)				
MCASP0_AXR13	GPIO0_41	40pin Expansion Header Signal (GPIO)	Bi-Dir	Expansion Board Specific (Pin 36)				
MCASP0_AXR14	GPIO0_42	40pin Expansion Header Signal (GPIO)	Bi-Dir	Expansion Board Specific (Pin 11)				
ECAP0_IN_APWM_OUT	GPIO0_49	SD Card IO Voltage Selection	Output	'0' – SD Card IO Voltage is 1.8 V '1' – SD Card IO Voltage is 3.3 V (default)				
TIMER_IO0	GPIO0_58	SD card detect signal	Input	Active Low Signal '0'- SD Card Detected '1'- SD Card Not Detected				
TIMER_IO1	GPIO0_59	USB VBUS Drive signal	Output	Active High Signal '0'- VBUS Disabled '1'- VBUS Enabled				

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3.5 I2C GPIO Expander Table

The EVM uses I2C-based IO expander(s) for some peripheral controls. The below table explains the functionality of the pins.

Table 3-4. I2C GPIO Mapping Table

PORT NO	Net name	Function	Dir/	Remarks
			Level	
		I2C Bus: I2C0, 0x21 (TC	A6416A)	'
P05	BOARDID_EEPROM_WP	EEPROM Write Protect	Output	'0' – EEPROM is NOT Write Protected (default) '1' – EEPROM is Write Protected
P06	CAN_STB	CAN Standby signal	Output	'0' – Normal Mode '1' – Standby Mode (default)
P10	GPIO_uSD_PWR_EN	SD Card Power Enable	Output	'0' – SD Card Power Disabled '1' – SD Card Power Enable (default)
P12	IO_EXP_PCle1_M.2_RTSz	M.2 Key M Interface Signal (RSTz)	Output	RSTz, See M.2 Key M specification for more details. (Default = '0')
P13	IO_EXP_MCU_RGMII_RST#	Ethernet PHY Reset	Output	'0' – Ethernet is Reset '1' – Ethernet is NOT Reset (default)
		I2C Bus: I2C1, 0x20 (TC	A6408A)	
P0	CSI_VIO_SEL	CSI I2C/GPIO Voltage Selection	Output	'0' – 1.8 V IO (default) '1' – 3.3 V IO
P1	CSI_SEL_FPC_EXPn	CSI Expansion Interface Selection	Output	CSI I2C MUX select '0' – Camera/Flex Selected (default) '1' – 40-pin Camera Expansion Selected
P2	IO_EXP_CSI2_EXP_RSTz	CSI Expansion Signal (RESETz)	Output	'0' – CSI Board is Reset (Default) '1' – CSI Board is NOT Reset
P3	CSI0_B_GPIO1	Camera #0 Flex Signal (PwrDwn)	Output	Camera Specific '0' – Normal Operation (default) '1' – Power Down
P4	CSI1_B_GPIO1	Camera #1 Flex Signal (PwrDwn)	Output	Camera Specific '0' – Normal Operation (default) '1' – Power Down
		I2C Bus: MCU_I2C1, 0x20	(TCA6408A)	
P0	HDMI_PDn	HDMI Transceiver Enable	Output	'0' – Power Down (default) '1' – Normal Operation
P1	HDMI_LS_OE	HDMI Monitor Enable	Output	'0' – Power Down '1' – Normal Operation (default)
P2	DP0_3V3_EN	Display Port Monitor Enable	Output	'0' – Monitor is Disabled (default) '1' – Monitor is Enabled
P3	eDP_ENABLE	DSI to eDP bridge Enable	Output	'1' – Bridge is Enabled(default) '0' – Bridge is Disabled

Note

In the DIR column, output is to the test automation module, input is from the test automation module. Bi-Dir signals can be configured as either input or output.

3.6 Identification EEPROM

The SK-AM68 board identified and revision information are stored in an on-board EEPROM. The first 259 bytes of memory are pre-programmed with EVM identification information. The format of that data is provided in Table 3-5. The remaining 32509 bytes are available for data or code storage.

The EEPROM is accessible from WKUP I2C0 port of processor at address 0x51 and 0x52

Table 3-5. Board ID memory Header information

Field Name	Offset / Size	Value	Comments
MAGIC	0000/ 4B	0xEE3355AA	Header Identifier
M_TYPE	0004/1B	0x1	Fixed length and variable position board ID header
M_LENGTH	0005/2B	0x37	Size of payload
B_TYPE	0007/1B	0x10	Payload type
B_LENGTH	0008/2B	0x2E	Offset to next header
B_NAME	000A/16B	J7AEP SK SOM/J7AEP BASE BOARD	Name of the board
DESIGN_REV	001A/2B	E1	Revision number of the design
PROC_NBR	001C/4B	131/125	PROC number
VARIANT	0020/2B	1	Design variant number
PCB_REV	0022/2B	E1	Revision number of the PCB
SCHBOM_REV	0024/2B	0	Revision number of the schematic
SWR_REV	0026/2B	1	First software release number
VENDORID	0028/2B	1	
BUILD_WK	002A/2B		Week of the year of production
BUILD_YR	002C/2B		Year of production
BOARDID	002E/6B	0	
SERIAL_NBR	0034/4B		Incrementing board number
DDR_INFO	TYPE	1	
	Length	2	Offset to next header
	DDRcontrol	2	DDR Control Word
MAC_ADDR	TYPE	1	Payload type
	Length	2	Size of payload
	MAC control	2	MAC header control word
	MAC_adrs	192	
END_LIST	TYPE	1	End Marker

4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from January 30, 2023 to October 31, 2025 (from Revision * (January 2023) to Revision A (October 2025))

Page

- Updated the numbering format for tables, figures and cross-references throughout the document.......
- Replaced TDA4VM EAIK with SK-TDA4VM throughout the document......1



Revision History

Added HDMI trademark information......1

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 - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
- 2 Limited Warranty and Related Remedies/Disclaimers:
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NOTE:

EXPOSURE TO ELECTROSTATIC DISCHARGE (ESD) MAY CAUSE DEGREDATION OR FAILURE OF THE EVALUATION KIT; TI RECOMMENDS STORAGE OF THE EVALUATION KIT IN A PROTECTIVE ESD BAG.

3 Regulatory Notices:

3.1 United States

3.1.1 Notice applicable to EVMs not FCC-Approved:

FCC NOTICE: This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

3.1.2 For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:

CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- · Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types lated in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur

3.3 Japan

- 3.3.1 Notice for EVMs delivered in Japan: Please see http://www.tij.co.jp/lsds/ti_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
 - https://www.ti.com/ja-jp/legal/notice-for-evaluation-kits-delivered-in-japan.html
- 3.3.2 Notice for Users of EVMs Considered "Radio Frequency Products" in Japan: EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

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- 1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
- 2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
- 3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above. User will be subject to penalties of Radio Law of Japan.

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- 3.3.3 Notice for EVMs for Power Line Communication: Please see http://www.tij.co.jp/lsds/ti_ja/general/eStore/notice_02.page 電力線搬送波通信についての開発キットをお使いになる際の注意事項については、次のところをご覧ください。https://www.ti.com/ja-jp/legal/notice-for-evaluation-kits-for-power-line-communication.html
- 3.4 European Union
 - 3.4.1 For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive):

This is a class A product intended for use in environments other than domestic environments that are connected to a low-voltage power-supply network that supplies buildings used for domestic purposes. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

- 4 EVM Use Restrictions and Warnings:
 - 4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.
 - 4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.
 - 4.3 Safety-Related Warnings and Restrictions:
 - 4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.
 - 4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.
 - 4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User's handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.
- 5. Accuracy of Information: To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.

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